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## **New VITA 91 High Density VPX Backplanes from Pixus**

Waterloo, Ontario — Apr 27, 2026 – Pixus Technologies, a provider of embedded computing and enclosure solutions, has announced a new line of VITA 91 compliant backplanes. The specification utilizes high density connectors for OpenVPX that doubles the potential data rate across the backplane.

The VITA 91 3U OpenVPX backplanes from Pixus have a mix of OpenVPX slots and double density slots. They can potentially support speeds up to 56Gbps across the backplane.

“The VITA 91 backplanes are a stepping stone to next-generation specifications such as VITA 100, leveraging high-density interconnects,” said Eran Weragama, Solution Architect at Pixus Technologies. “Experience in higher density and faster signal speed interfaces is critical for mastering advanced backplane technologies.”

Pixus provides backplanes, enclosure systems, and chassis managers for OpenVPX and other VITA-based designs. The company provides ruggedized enclosure solutions in conduction-cooled, air-cooled, Air Flow Through (AFT), and Liquid Flow Through (LFT) formats.

### **About Pixus Technologies**

Leveraging over 20 years of innovative standard products, the Pixus team is comprised of industry experts in electronics packaging. Founded in 2010, Pixus Technologies' embedded backplanes and chassis platforms are focused primarily on OpenVPX and other VITA based MOSA standards. Pixus also has an extensive offering of VME, cPCI, and xTCA solutions. The company also ruggedizes NI/Emerson SDRs and provides customized solutions tailored to a customer’s specific application.

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